

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc1147hvcs8-3.3#trpbf

(Engineering Calculation)

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TOTAL MASS (g) : 0.075436

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003629 | 1000000 | 48107.09375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.023653 | 975000 | 313551.15625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000582 | 24000 | 7715.1640625 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000007 | 300 | 92.7940673828 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000017 | 700 | 225.357025146 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.024259 | 1000000 | 321584.46875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001477 | 1000000 | 19577.5878906 | | |
| | | External Plating Total: | | | | 0.001477 | 1000000 | 19577.5878906 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000194 | 1000000 | 2571.72143555 | | |
| Internal Plating Total: | | | | 0.000194 | 1000000 | 2571.72143555 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001040 | 750000 | 13786.5478516 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000347 | 250000 | 4599.93457031 | | |
| Die Attach Total: | | | | 0.001387 | 1000000 | 18386.4804688 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006657 | 150000 | 88247.1640625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.036392 | 820000 | 482423.09375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.001110 | 25000 | 14714.4882812 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000222 | 5000 | 2942.89770508 | | |
| | | Encapsulation Total: | | | | 0.044381 | 1000000 | 588327.625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000109 | 1000000 | 1444.9362793 | | |
| | | | | | TOTAL MASS (g) : | 0.075436 | | |